	Hits	Search Text	DBs
3	73	(IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4) same fuse) and (fuse same (metal$4 or conduct$4 or Cu)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	77	(IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4) same fuse) and (fuse same (metal$4 or conduct$4 or Cu)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	42	(IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4) same fuse) and (fuse same (metal$4 or conduct$4 or Cu)) and ((terminal or interconnect$4) same ((integrated near5 circuit$4) or IC)) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	39	(IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or cut$4) same fuse same (resist or photoresist or photolithgraph$6 or lithograph$7)) and (fuse same (metal$4 or conduct$4 or Cu)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
7	0	430/311.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	0	430/945.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
9	0	430/313.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	1	"430"/$.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
11	12	257/529.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	3	257/762.ccls. and (IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
13	77	(IC or (integrated near5 circuit$4)) and ((open$4 or etch$4 or remov$4 or blow$4 or ablat$4 or (delet$4 near9 laser)) same fuse) and (fuse same (metal$4 or conduct$4 or Cu or copper)) and (terminal or interconnect$4) and (barrier or (diffus$4 near5 barrier)) and (etch$4 same (dry or wet)) and ((resist or photoresist) same (expos$4 or illuminat$4 or irradiat$4)) and develop$4 and pattern$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB